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Application ID: 10766046



Title of Invention:

LEADFRAME TYPE
SEMICONDUCTOR PACKAGE
HAVING REDUCED INDUCTANCE
AND ITS METHOD

First Named Inventor: GI KIM

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TRANSMITTAL

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Title of Invention	LEADFRAME TYPE SEMICONDUCTOR PACKAGE HAVING REDUCED INDUCTANCE AND ITS METHOD									
<p>Application Number: 10/766046 </p> <p>Date: 2004-01-28</p> <p>First Named Applicant: GI JEONG KIM</p> <p>Confirmation Number: 2288</p> <p>Attorney Docket Number: AMKOR099A</p>										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney		
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MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
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Documents being submitted	Files									
us-ids	ids2-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

LEADFRAME TYPE SEMICONDUCTOR PACKAGE
HAVING REDUCED INDUCTANCE AND ITS METHOD

Application Number: 10/766046



Confirmation Number: 2288

First Named Applicant: GI KIM

Attorney Docket Number: AMKOR099A

Art Unit: 2613

Search string: (5216278 or 5218231 or 5221642 or 5250841
or 5252853 or 5258094 or 5266834 or 5273938
or 5277972 or 5278446 or 5279029 or 5281849
or 5294897 or 5327008 or 5332864 or 5335771
or 5336931 or 5343076 or 5358905 or 5365106
or 5381042 or 5391439 or 5406124 or 5410180
or 5414299 or 5417905 or 5424576 or 5428248
or 5435057 or 5444301 or 5452511 or 5454905
or 5474958 or 5484274 or 5493151 or 5508556
or 5517056 or 5521429 or 5528076 or 5534467
or 5539251 or 5543657 or 5544412 or 5545923
or 5581122 or 5592019 or 5592025 or 5594274
or 5595934 or 5604376).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date